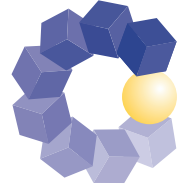
**1****Manufacturing of components**

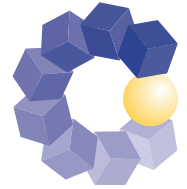
- 1.1** Electronic manufacturing services (EMS)
 - 1.1.1 Electronics designing
 - 1.1.2 Electronics development
 - 1.1.3 Electronics manufacturing
 - 1.1.4 Electronics assembly
 - 1.1.5 Electronics testing
 - 1.1.6 Cable assembly
 - 1.1.7 Electronis full service
 - 1.2** Plastics processing
 - 1.2.1 Injection molding
 - 1.2.2 Extrusion
 - 1.2.3 Polyurethane processing (PUR)
 - 1.2.4 Plastic welding
 - 1.2.5 Plastics processing full service
 - 1.3** Toolmaking, mold making
 - 1.4** Metal machining processing
 - 1.4.1 Molding
 - 1.4.2 Forging
 - 1.4.3 Metal cutting, chip removal
 - 1.5** Surface treatment
 - 1.5.1 Mechanical surface refinement
 - 1.5.2 Thermic surface finishing
 - 1.5.3 Surface coating
 - 1.6** Laser processing
 - 1.6.1 Laser cutting
 - 1.6.2 Laser welding
 - 1.6.3 Laser marking
 - 1.7** Additive manufacturing, 3D printing
 - 1.8** Rapid prototyping
 - 1.9** Other component manufacturing
- 2** **Manufacturing of finished products**
- 2.1** Therapeutic products, medical technical aids
 - 2.2** Catheters
 - 2.3** Cannula
 - 2.4** Stents
 - 2.5** Needles
 - 2.6** Surgical instruments
 - 2.7** Implants (passive)
 - 2.8** Implants (active)
 - 2.8.1 Cardiac pacemakers
 - 2.8.2 Defibrillators
 - 2.8.3 Cochlea implants
 - 2.8.4 Neuro-stimulators

- 2.8.5** Insuline pumps
 - 2.9** Electromedical devices
 - 2.10** Endoscopes
 - 2.11** Wearables
 - 2.12** Dental products
 - 2.13** OR infrastructure
 - 2.14** Rehabilitation technologies
 - 2.14.1 Orthopaedic aids
 - 2.14.2 Mobility aids, walking aids
 - 2.15** In-vitro diagnostics (IVD)
 - 2.16** Laboratory technologies
 - 2.16.1 Lab-on-a-chip
 - 2.16.2 Laboratory automation
 - 2.16.3 Liquid handling
 - 2.16.4 Pipettes
 - 2.16.5 Pipettes systems
 - 2.17** Biomedical products
 - 2.18** Other finished products
- 3** **Services**
- 3.1** Financing and funding
 - 3.2** Consulting (services)
 - 3.2.1 Market access, internationalization
 - 3.2.2 Patents, intellectual property (IP)
 - 3.2.3 Education, training
 - 3.2.4 Regulatory affairs
 - 3.2.5 Documentation
 - 3.2.6 Clinical trials
 - 3.2.7 Medical device approval
 - 3.3** Research
 - 3.4** Design and development
 - 3.4.1 Product design, product development
 - 3.4.2 Packaging design, packaging development
 - 3.4.3 Production layout
 - 3.5** Assembly
 - 3.6** Contract packaging
 - 3.7** Labeling
 - 3.8** Sterilization
 - 3.9** Testing services
 - 3.9.1 Material testing
 - 3.9.2 Functional testing
 - 3.9.3 Environmental testing
 - 3.9.4 Safety testing



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3.9.5	Certification	5.10	Construction elements
3.9.6	Auditing	5.11	Guide wire
3.10	Other services	5.12	Tubings and tubing equipment
4	Manufacturing equipment	5.13	Other components, modules, OEM equipment
4.1	Injection molding machines	6	Electrical components, electrical components
4.2	Extruders	6.1	Sensors
4.3	Machine tools and peripheral equipment	6.1.1	Distance sensors, displacement sensors
4.4	Laser processing equipment	6.1.2	Imaging sensors
4.5	Additive processing equipment, 3D printers	6.1.3	Biosensors
4.6	Automation, robotics	6.1.4	Pressure sensors
4.7	Assembly systems	6.1.5	Flow sensors
4.8	Dosing	6.1.6	Gas sensors
4.9	Cleanroom technology	6.1.7	Temperature sensors
4.10	Enterprise Resource Planning (ERP), Manufacturing Execution System (MES)	6.2	Electromechanical components
4.11	Quality assurance	6.2.1	Cables
4.11.1	Computer aided quality assurance (CAQ)	6.2.2	Plugs, connectors
4.11.2	Quality measurement systems (QMS)	6.2.3	Enclosures
4.11.3	Measuring technology, testing technology	6.2.4	Switches
4.12	Packaging machines	6.3	Electrooptical components
4.13	Labeling machines	6.4	Semiconductors, integrated circuits (IC)
4.13.1	Product labeling	6.4.1	Microprocessors
4.13.2	Packaging labeling	6.4.2	Microcontrollers
4.14	Other manufacturing equipment	6.4.3	Application-specific integrated circuits (ASICs), custom chip
5	Components, modules, OEM equipment	6.4.4	RFID chips
5.1	Electrical motors	6.5	Circuit boards
5.2	Pneumatic actuators	6.6	Organic electronics
5.3	Linear technology	6.7	Embedded systems
5.4	Plain bearings, rolling bearings	6.8	Power supply
5.5	Pumps	6.8.1	Batteries
5.6	Valves	6.8.2	Accumulators
5.7	Filters	6.8.3	Power supply equipment
5.8	Optical components	6.8.4	Uninterruptible power supply (UPS)
5.9	IV components	6.8.5	Fuel cells
		6.8.6	Energy harvesting
		6.9	Lamps
		6.10	LED technology
		6.11	Displays
		6.12	Imaging systems
		6.13	Camera systems
		6.14	Other electrical / electrical components



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7**Microtechnology****7.1**

Mechatronics

7.2

Micromechanics

7.3

Microactuators

7.4

Microsensors

7.5

Microelectronics

7.6

Microoptics

7.7

Microfluidics

7.8

Microprocessing

7.8.1

Micromolding

7.8.2

Printed electronics

7.8.3

Laser structuring

7.8.4

Etching

7.9

Microassembly

7.10

Nanotechnology

7.11

Other microtechnology

8**Raw materials, materials, adhesives****8.1**

Plastics

8.2

Metals

8.3

Ceramics

8.4

Composites

8.5

Semi-finished products

8.6

Glass

8.7

Packaging materials

8.8

Adhesives

8.9

Other raw materials, materials, adhesives

9**Software, IT****9.1**

Imaging

9.2

Augmented reality, virtual reality (VR)

9.3

Software development

9.4

Software as a medical product

9.5

E-Health

9.6

Medical apps

9.7

Data security

9.8

Cyber security

9.9

WiFi, radio transmission

9.10

Remote maintenance, predictive maintenance

9.11

Cloud services

9.12

Big data

9.13

Other software, IT